

# Additive Manufacturing – Module 2

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# What is AM

What is AM

Applications

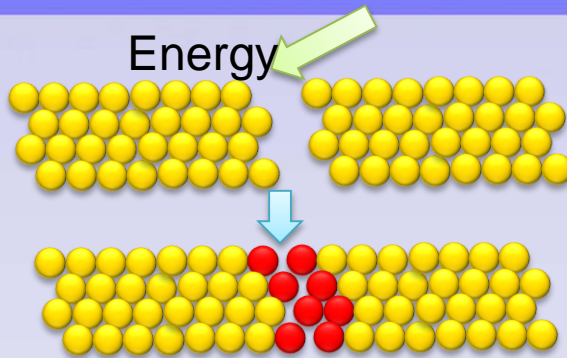
How does it work

Advantages

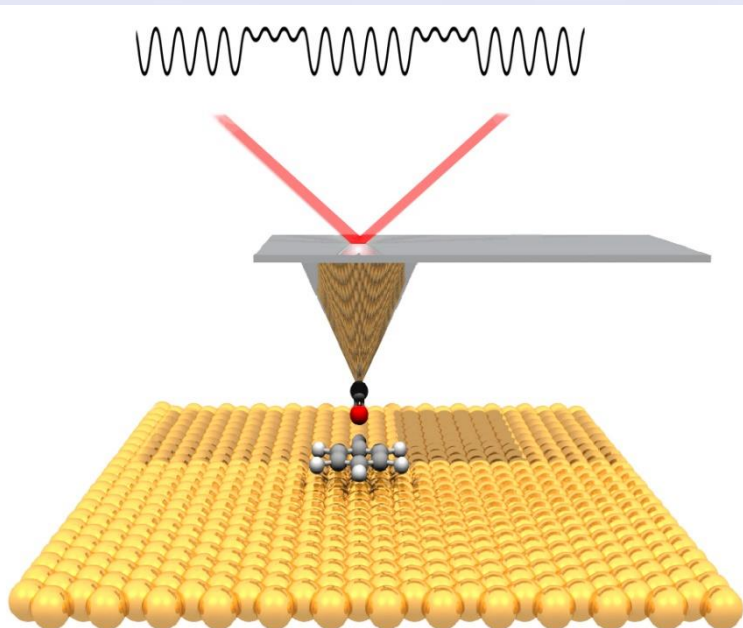
Opportunities

Challenges

AM Industry



**Additive:** reducing material interface between material particles



Build atom by atom, bond by bond



Lego

- ❖ **Material units (atom, droplets, powder particles, etc.)**
- ❖ **Bonding/joining mechanism (need to form new bonds between material units)**
- ❖ **Controlled (forming new bonds in a controlled fashion)**
- ❖ **Source of control (pattern energy or materials or both)**

# What is AM

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Applications

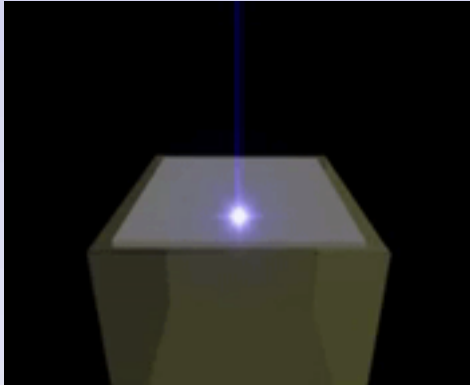
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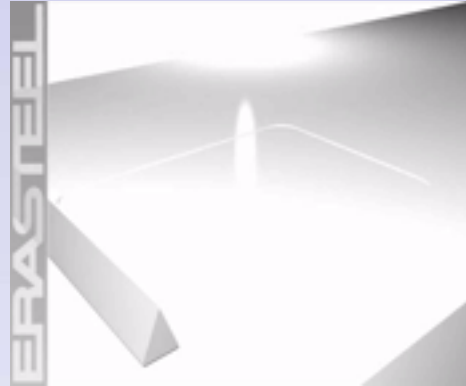
Opportunities

Challenges

AM Industry



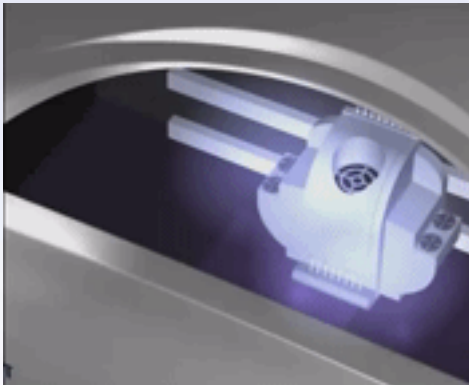
Stereolithography



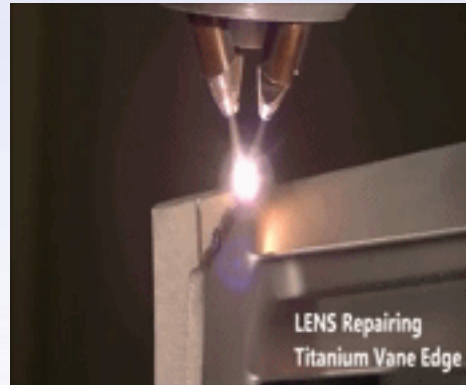
Selective Laser Melting  
Powder bed fusion processes



Fused Deposition Modeling  
Extrusion based processes



Inkjet deposition  
Printing based processes



Laser Engineered Net  
Shaping Beam deposition  
processes



Laminated Object  
Manufacturing Sheet  
lamination processes

# What is AM

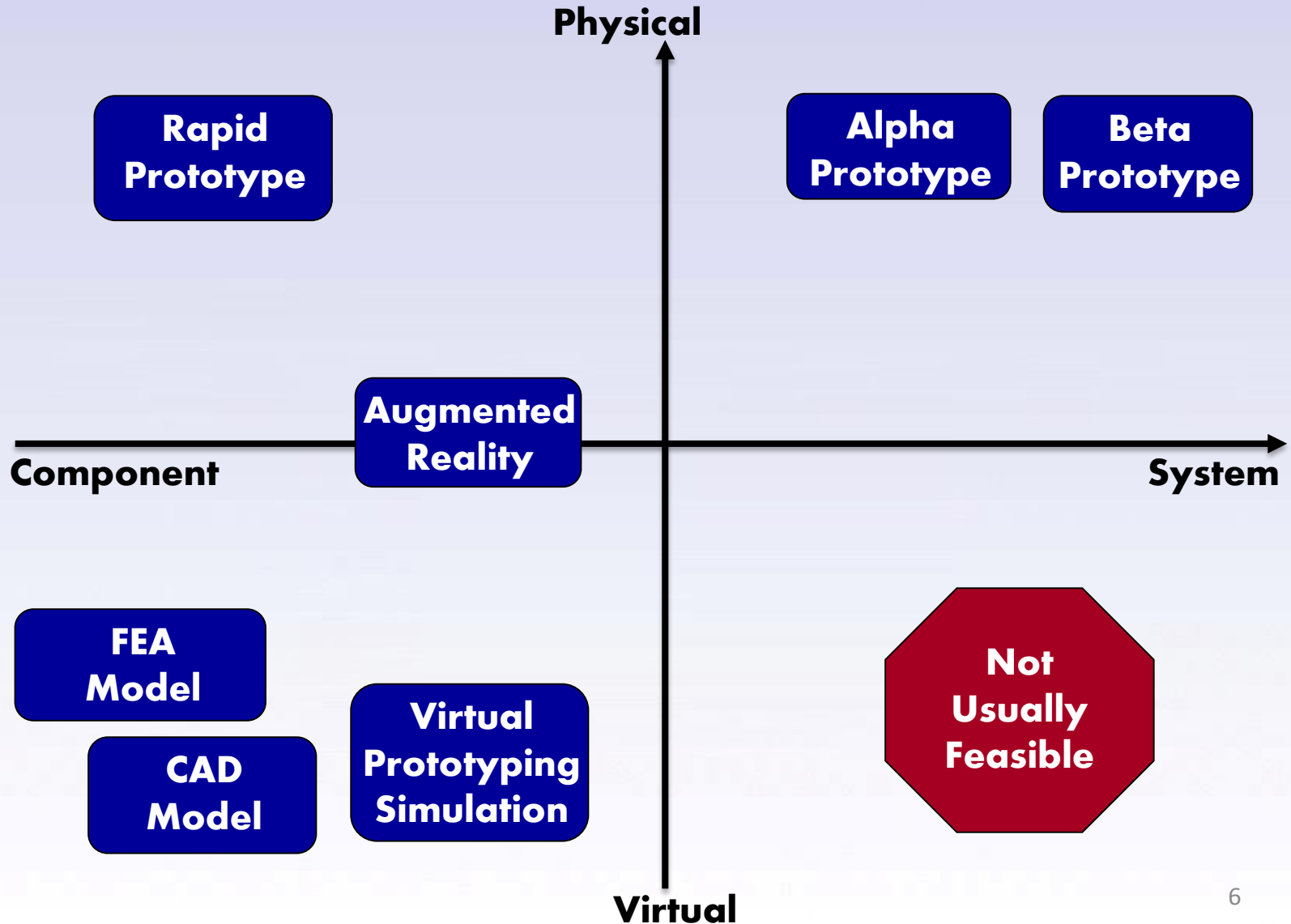
- ❖ **Stereolithography (SLA) - 3D Systems**
- ❖ **Selective Laser Sintering (SLS) - 3D Systems, EOS**
- ❖ **Fused Deposition Modeling (FDM) - Stratasys**
- ❖ **3D Printing Technology (3DP) - Z Corp. (now 3D Systems), Ex One**
- ❖ **Inkjet - 3D Systems; Objet, Solidscan (now both Stratasys)**
- ❖ **Laser Engineered Net Shaping (LENS) – Optomec**
- ❖ **Direct Metal Deposition (DMD) – POM Group**
- ❖ **Solid Ground Curing (SGC) Cubital (out of business 2000)**
- ❖ **Ultrasonic Consolidation (UC or UAM) – Solidica (Fabrisonic)**
- ❖ **Laminated Object Manufacturing (LOM) – Helisys (Now Cubic Tech) & MCOR**

# What is AM

		1D	2D
What is AM		<b>Point Scanning</b>	<b>Area Filling</b>
Applications			
How does it work	<b>Pattern Material</b>	<b>FDM</b>	<ul style="list-style-type: none"> <li>• <b>Inkjet (binder or material)</b></li> <li>• <b>LOM</b></li> <li>• <b>Ultrasonic Consolidation</b></li> </ul>
Advantages			
Opportunities			
Challenges	<b>Pattern Energy</b>	<ul style="list-style-type: none"> <li>• <b>Stereolithography</b></li> <li>• <b>Selective Sintering (laser or E-beam)</b></li> <li>• <b>Selective Melting</b></li> <li>• <b>LCVD (Georgia Tech)</b></li> <li>• <b>Electrochemical Deposition</b></li> </ul>	<ul style="list-style-type: none"> <li>• <b>Micro-SL with DMD (or DLP)</b></li> <li>• <b>Solid Ground Curing</b></li> </ul>
AM Industry	<b>Pattern Both</b>	<b>LENS/DMD</b>	

# Applications

## ♦ Prototyping – Types of prototypes





# Applications

## ❖ Prototyping – Design Applications

- ❖ Feel
- ❖ Assembly
- ❖ Motion/functions

❖ Visualization  
❖ Communication  
❖ Marketing

**Concept  
Models**

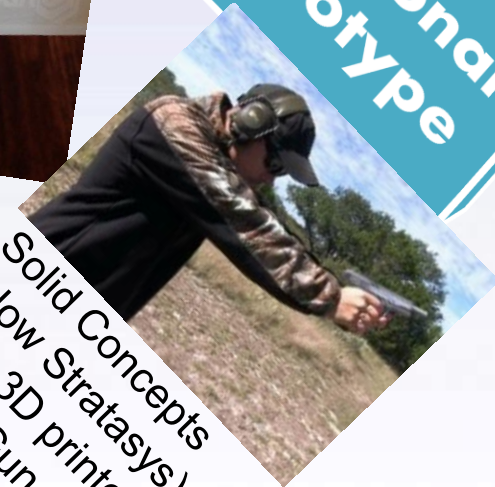


**Form-fit  
Models**



**Functional  
Prototype**

❖ Subject to testing



Solid Concepts  
(Now Stratasys),  
First 3D printed  
Metal Gun, 2013

# Applications

What is AM

Applications

How does it work

Advantages

Opportunities

Challenges

AM Industry



Aerospace (parts & repairing)



Art, Fashion, Jewelry

Hearing aid - Siemens



Align Technology



Automotive (RP & tooling)

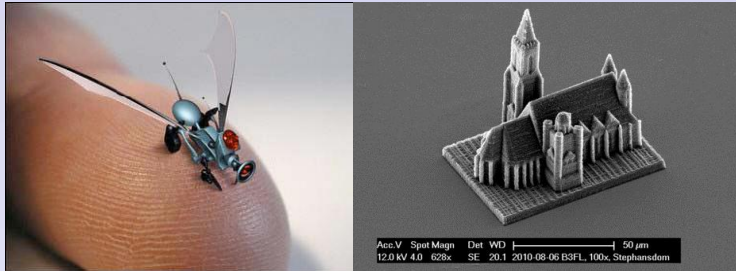


Skull implants, 2011, by Xilloc Medical

[enablingthefuture.org](http://enablingthefuture.org)



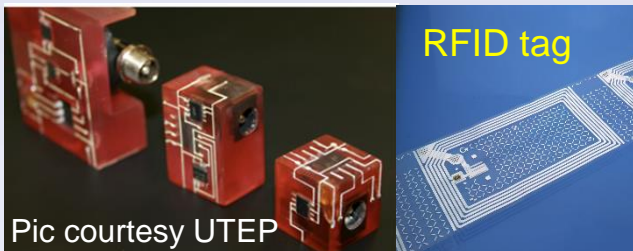
## ◆ Prototyping – Design Applications



3D nano-printing



Food



Pic courtesy UTEP

Printed electronics (structural electronics, lightweight, integrated)



Entertainment (movie, Hollywood)

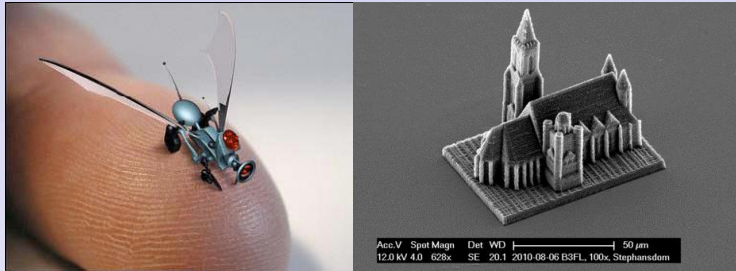


Bioprinting



Education

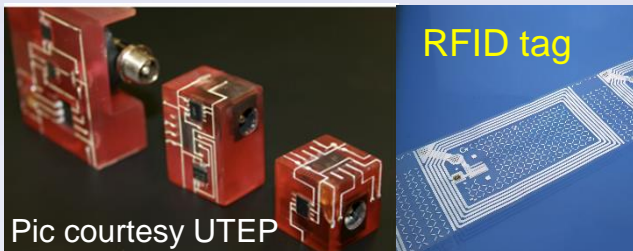
## ♦ Prototyping – Design Applications



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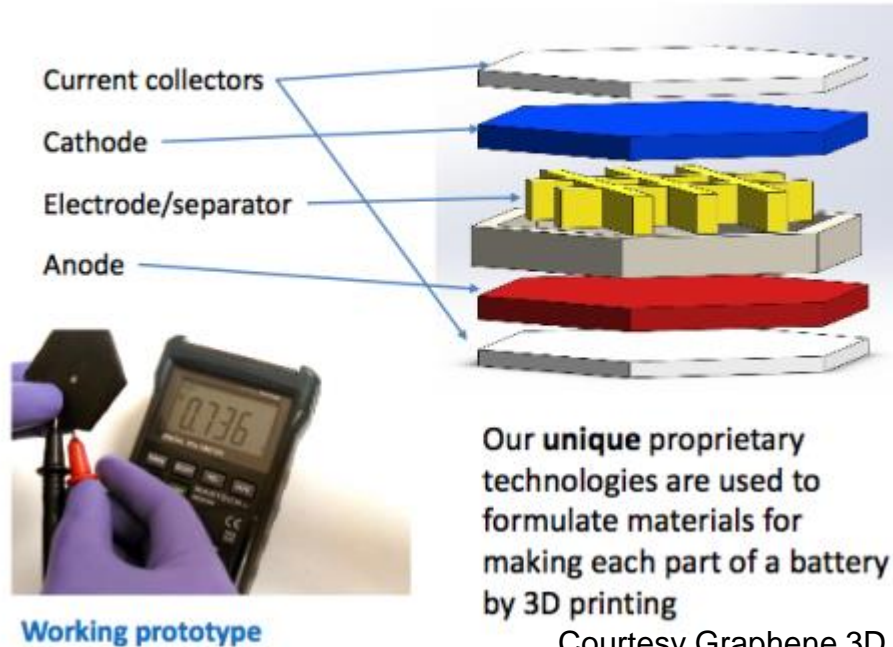
Bioprinting



Education



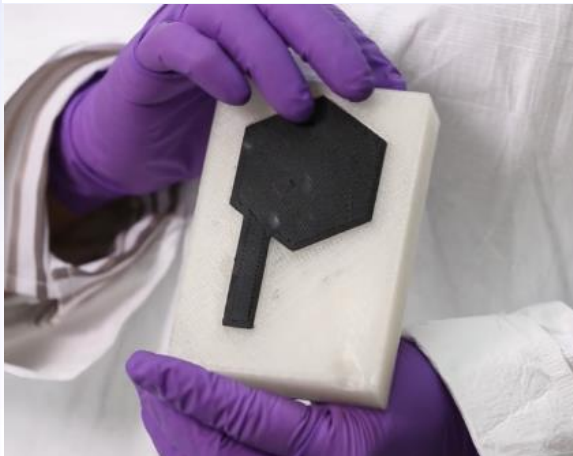
## Emerging Technology: 3D Printed Battery



Courtesy Graphene 3D Lab

Need **MORE KILLER** Apps

Energy devices (battery, supercapacitors)



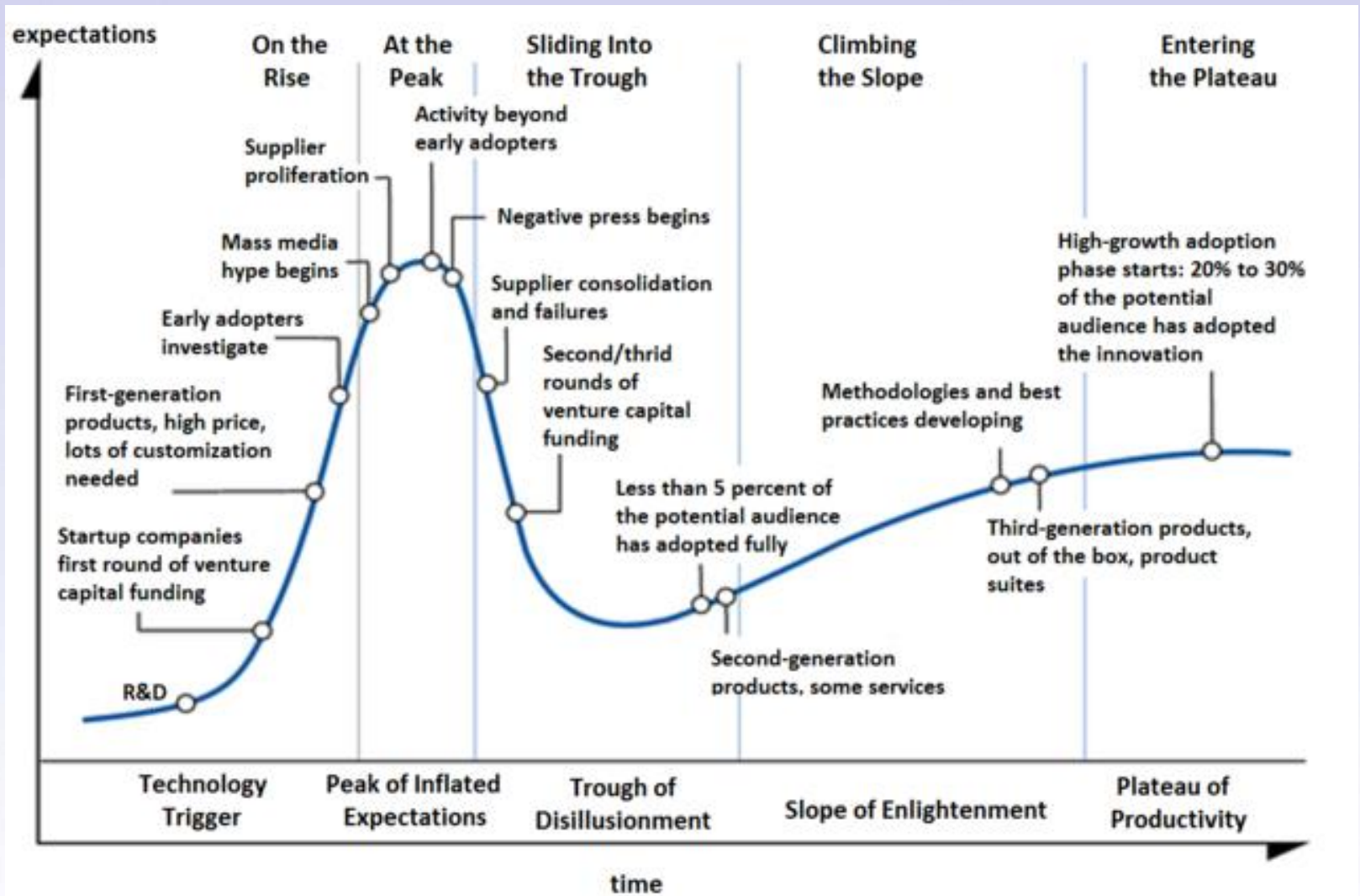
Need **MORE**  
**KILLER** Apps



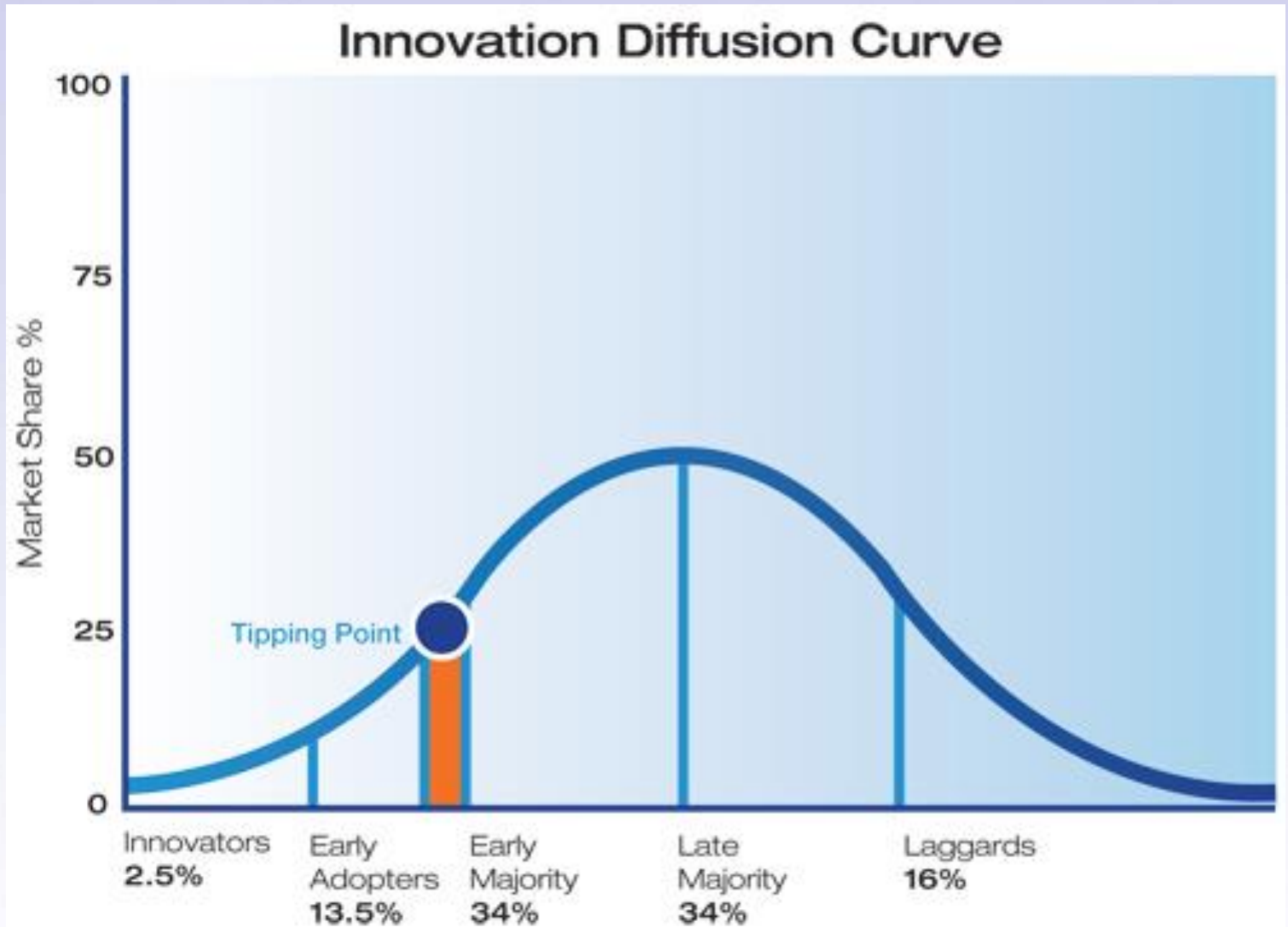
WinSun New Materials, Ma Yihe, Printing 10 homes in 24 hours

<http://blogs.wsj.com/chinarealtime/2014/04/15/how-a-chinese-company-built-10-homes-in-24-hours/>

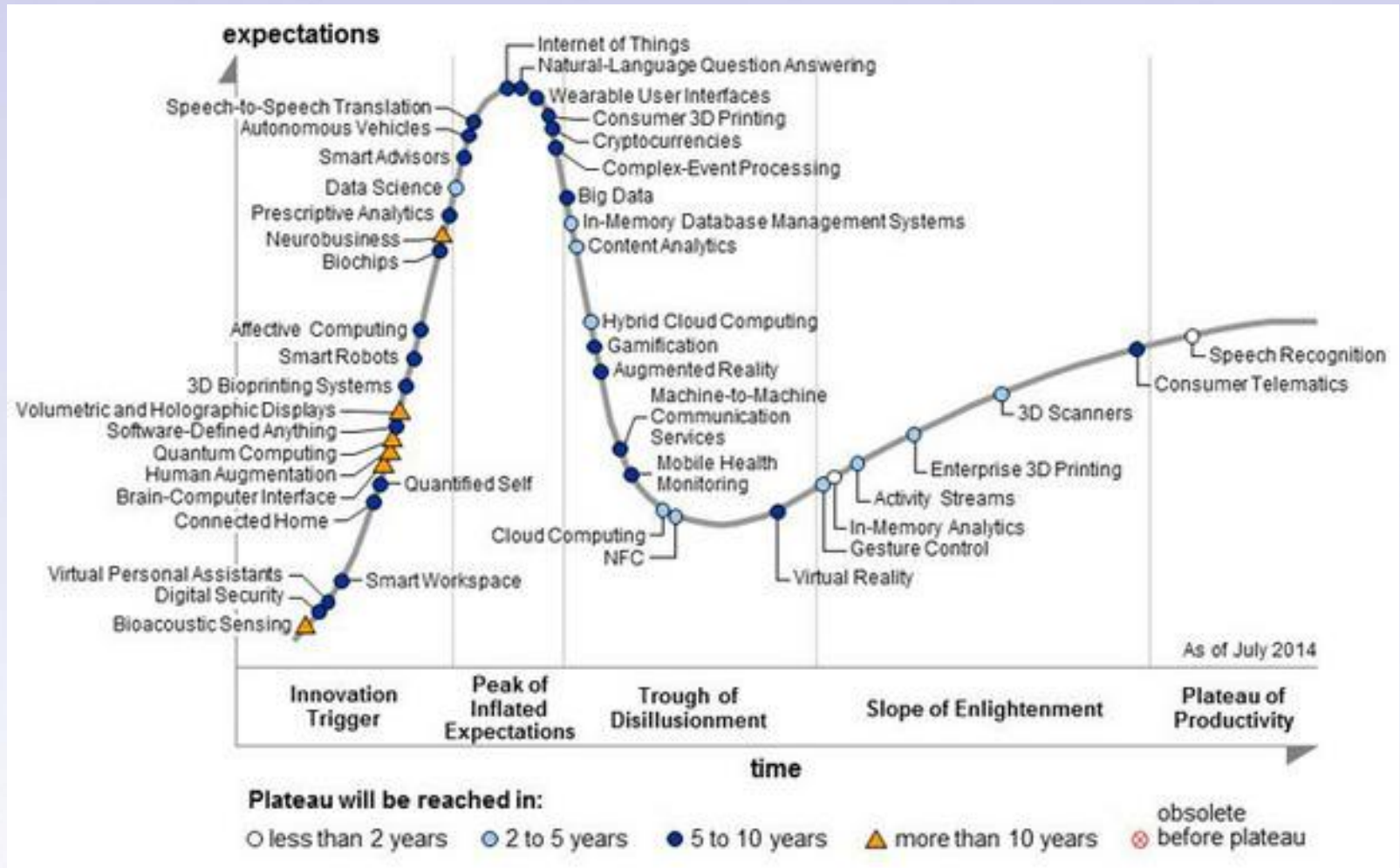
# Applications







# Applications



# How does it Work

What is AM

Applications

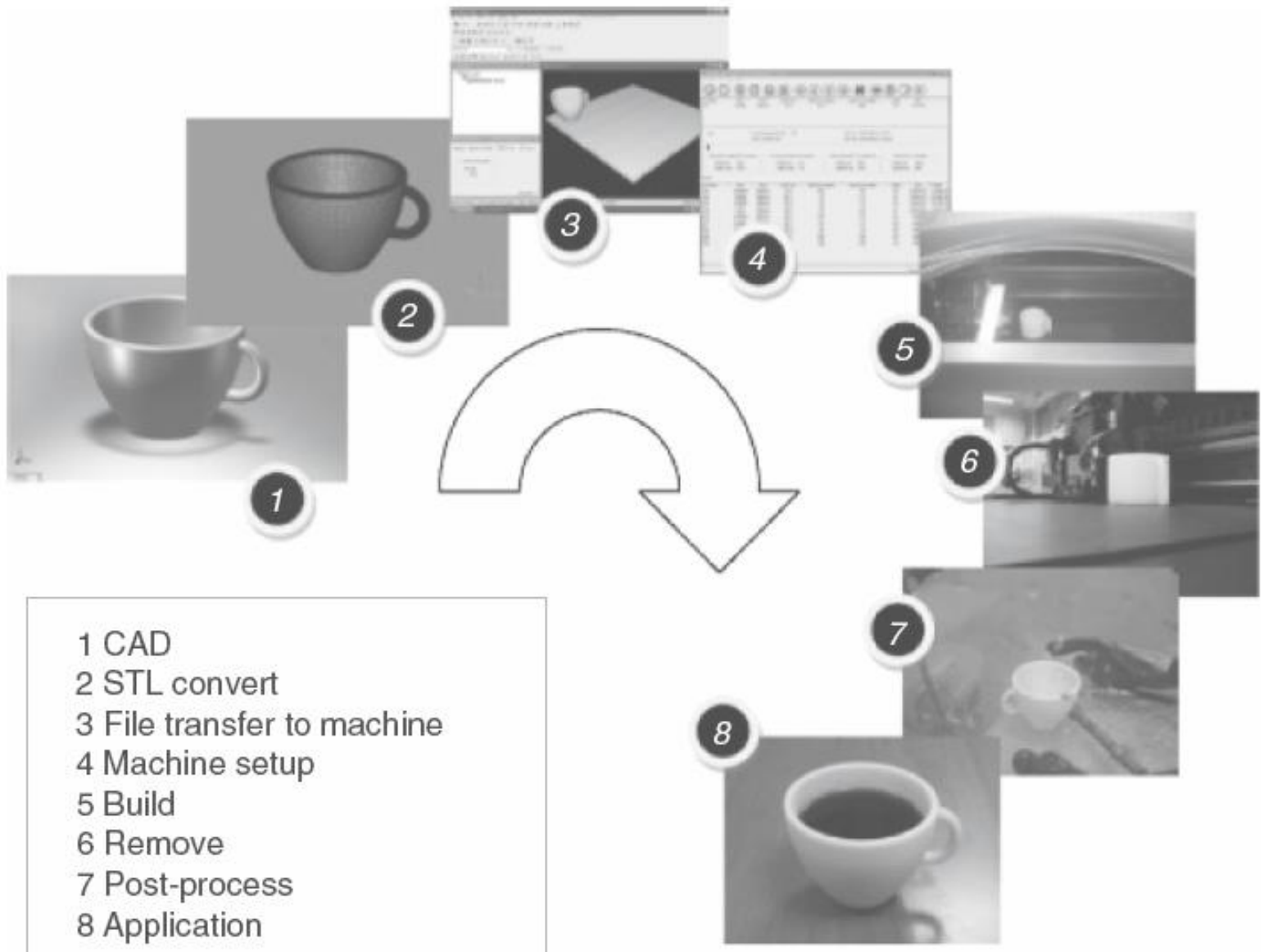
How does it work

Advantages

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AM Industry



## File Format – STL

solid name

facet normal ni nj nk

outer loop

vertex v1x v1y v1z

vertex v2x v2y v2z

vertex v3x v3y v3z

endloop

endfacet

facet normal ni nj nk

outer loop

vertex v1x v1y v1z

vertex v2x v2y v2z

vertex v3x v3y v3z

endloop

endfacet

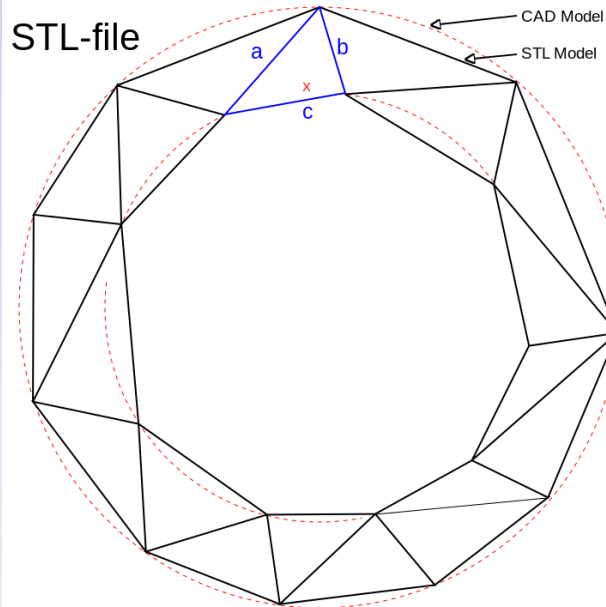
.

.

.

endsolid name

STL-file



Developed by 3D Systems: quasi-industrial standard  
Name from the original technology: STereoLithography  
ASCII or Binary format exist

### Information Missing:

- ❖ **Color (Some systems added, e.g., VisCAM)**
- ❖ **Materials**
- ❖ **Process parameters**

**Triangular “Soup”**

## File Format – AMF

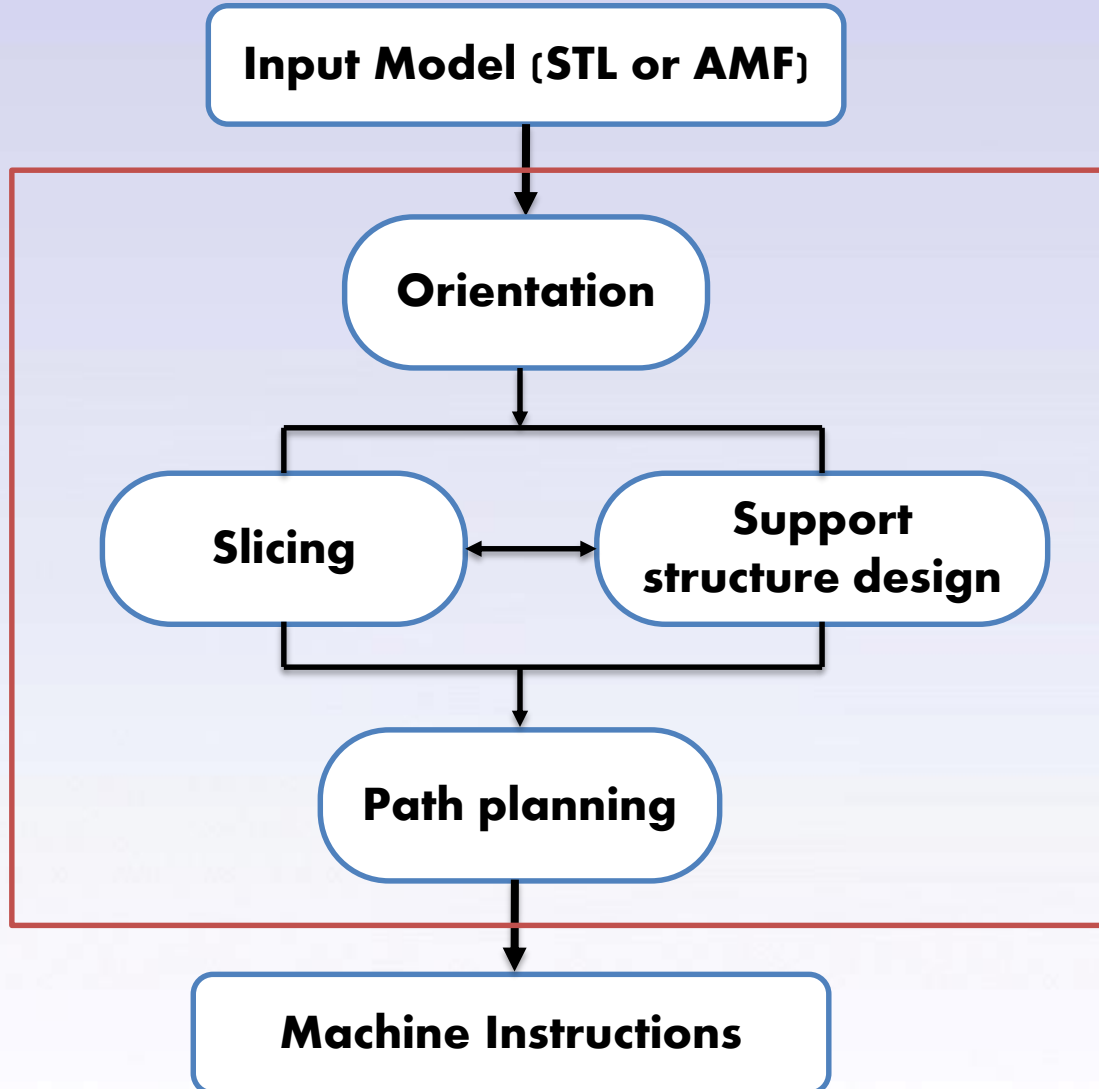
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  <metadata type="author">John Smith</metadata>
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    <mesh>
      <vertices>
        <vertex><coordinates><x>0</x><y>0</y><z>0</z></coordinates></vertex>
        <vertex><coordinates><x>1</x><y>0</y><z>0</z></coordinates></vertex>
        <vertex><coordinates><x>0</x><y>1</y><z>0</z></coordinates></vertex>
        <vertex><coordinates><x>1</x><y>1</y><z>0</z></coordinates></vertex>
        <vertex><coordinates><x>0.5</x><y>0.5</y><z>1</z></coordinates></vertex>
      </vertices>
      <volume materialid="2">
        <metadata type="name">Hard side</metadata>
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        <triangle><v1>0</v1><v2>1</v2><v3>4</v3></triangle>
        <triangle><v1>4</v1><v2>1</v2><v3>2</v3></triangle>
        <triangle><v1>0</v1><v2>4</v2><v3>2</v3></triangle>
      </volume>
      <volume materialid="3">
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        <triangle><v1>1</v1><v2>3</v2><v3>4</v3></triangle>
        <triangle><v1>4</v1><v2>3</v2><v3>2</v3></triangle>
        <triangle><v1>4</v1><v2>2</v2><v3>1</v3></triangle>
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  </material>
  <material id="3">
    <metadata type="name">Soft material</metadata>
    <color><r>0</r><g>0.9</g><b>0.9</b><a>0.5</a></color>
  </material>
</amf>
```

- ◆ Additive Manufacturing File
- ◆ ISO/ASTM Standard, 2011
- ◆ Machine independent (no layer or process information)
- ◆ XML-based format
  - ◆ <object>: volume of materials
  - ◆ <material>
  - ◆ <texture>
  - ◆ <metadata>
  - ◆ ...



# How does it Work

## ❖ Software pipeline – From model to machine instructions



- ❖ **Orientation**
- ❖ **Support structure**
- ❖ **Slicing**
- ❖ **Path planning**
- ❖ **Machine instructions**

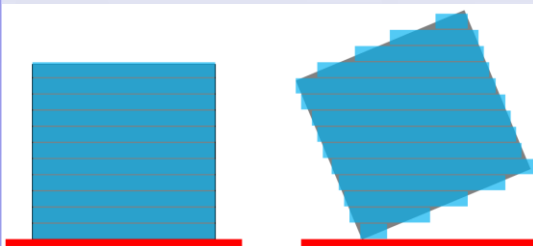
# How does it Work

## ❖ Orientation Determination

### Factors

- ❖ Surface accuracy
- ❖ Build time
- ❖ Support volume
- ❖ Support contact area
- ❖ Mechanical properties

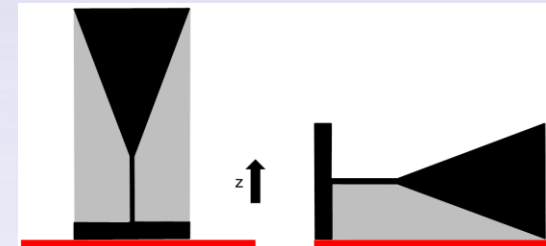
- ❖ **Orientation**
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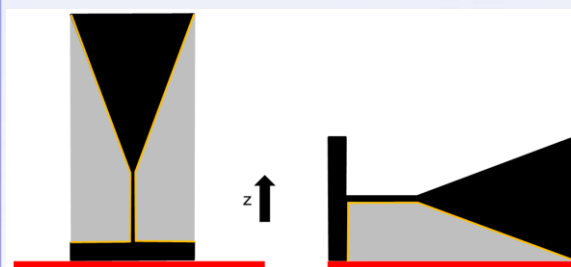
Surface accuracy



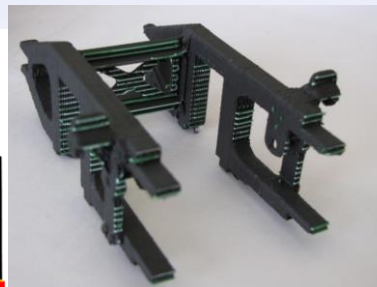
Build time



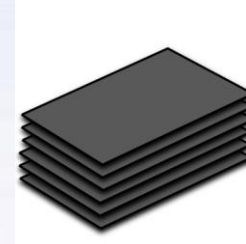
Support material volume



Support contact area



After support removal



Mechanical property (weaker in Z direction)



- ❖ Manual: user
- ❖ Semi-auto: user and software
- ❖ Auto: software

# How does it Work

## ❖ Support structure design

- ❖ “Powder” bed based processes: Do NOT need support structures: SLS, SLM, etc.
- ❖ Others DO: SLA, FDM, Inkjet deposition, etc.

## Objectives

- ❖ Prevent curling due to internal stress
- ❖ Supporting overhangs
- ❖ Maintaining stability

- ❖ Orientation
- ❖ **Support structure**
- ❖ Slicing
- ❖ Path planning
- ❖ Machine instructions

## Empirical “rules”



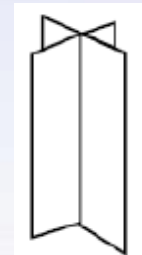
Inkjet



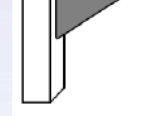
FDM (up to 45 degrees)

## Support types

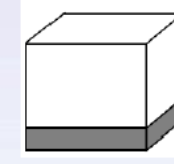
Column (SLA)



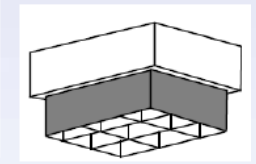
Gusset



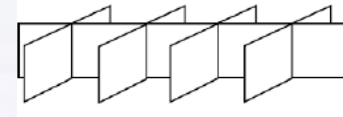
Base



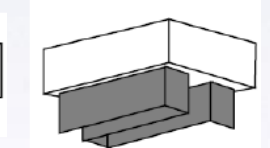
Perimeter&hatch



Web (SLA)



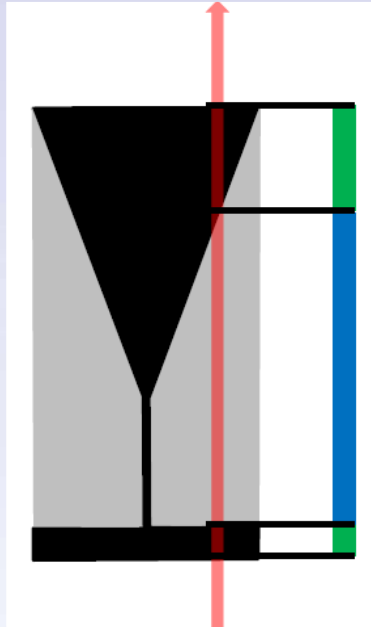
Zigzag (FDM)



## ❖ Support structure design

### Algorithms for generating support structures

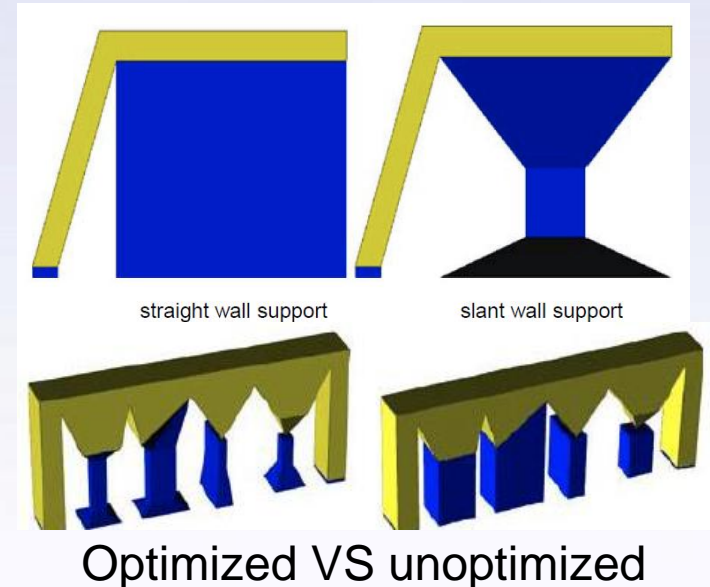
#### ❖ Simple ray casting algorithm



- ❖ Orientation
- ❖ **Support structure**
- ❖ Slicing
- ❖ Path planning
- ❖ Machine instructions

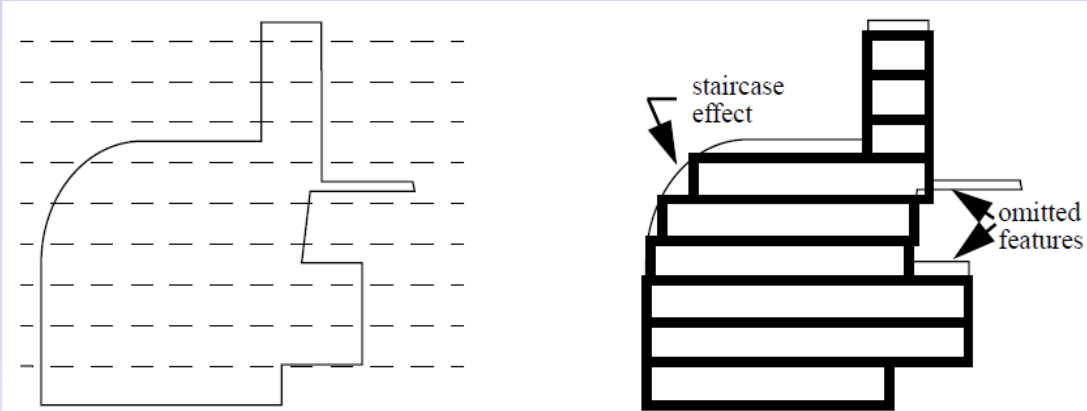
### Advanced algorithms

- ❖ Minimize the use of support material
- ❖ Or for other purposes, such as minimize curling



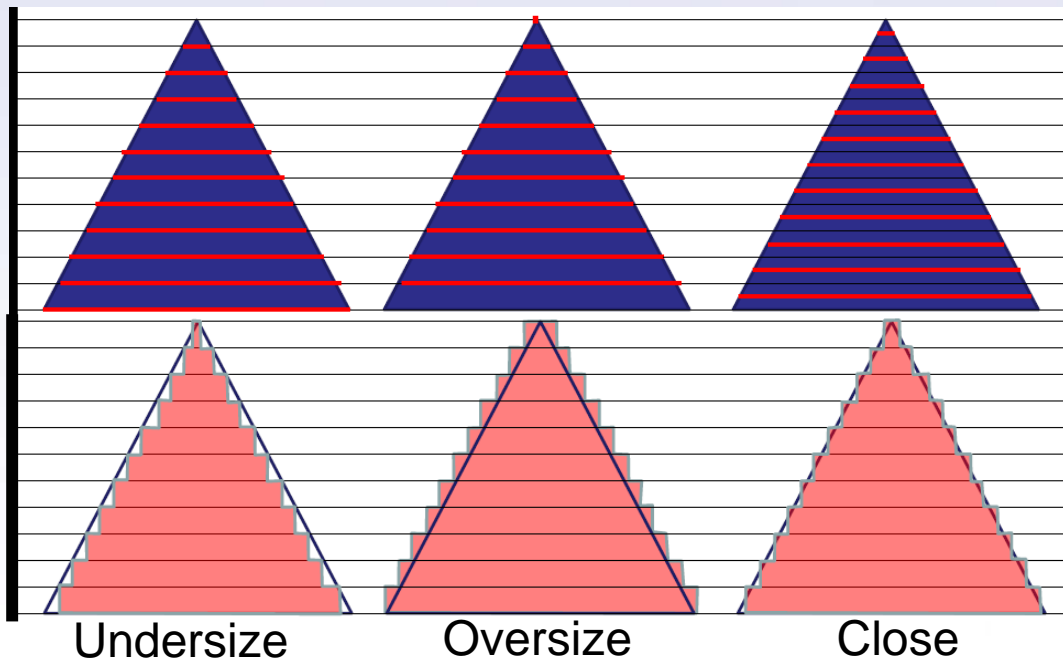
# How does it Work

## ❖ Slicing



- ❖ Orientation
- ❖ Support structure
- ❖ **Slicing**
- ❖ Path planning
- ❖ Machine instructions

For each  $z$ , compute intersection of a plane with the model





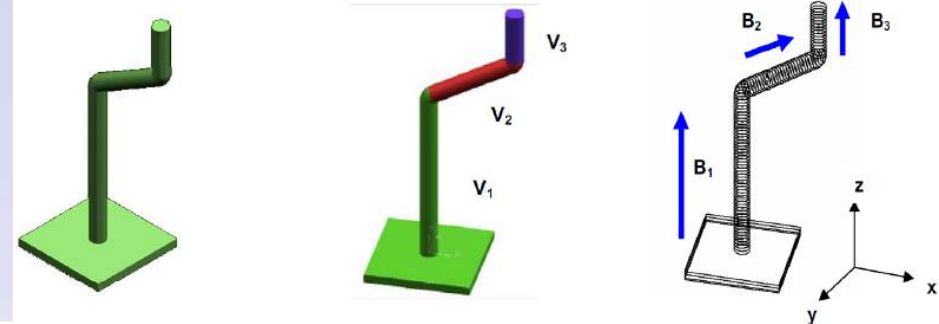
# How does it Work

## ❖ Slicing

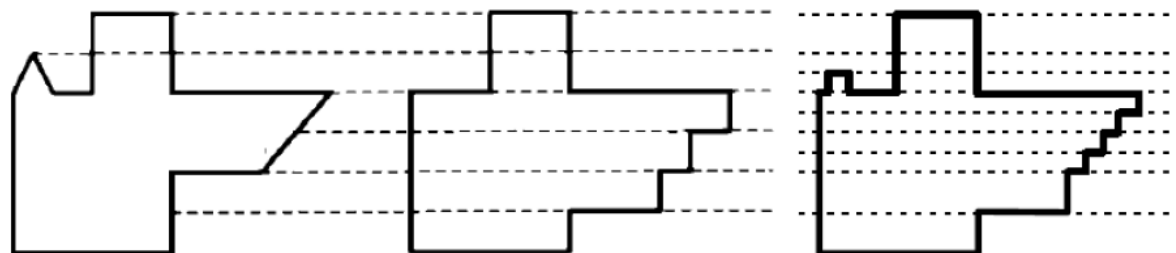
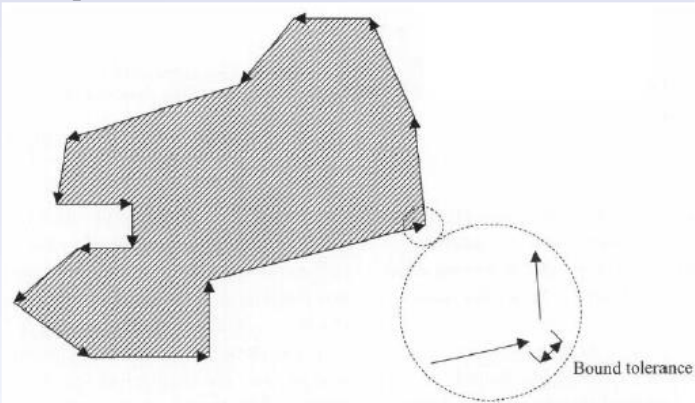
### Slicing STL

- ❖ **Voxelization (determine inside or outside)**
- ❖ **Then extract contours**
- ❖ **Epsilon issues (machine precision)**

## Many research on slicing



## Multi-direction slicing



input model

uniform slicing

adaptive slicing

## Adaptive slicing

# How does it Work

## ◆ Path planning

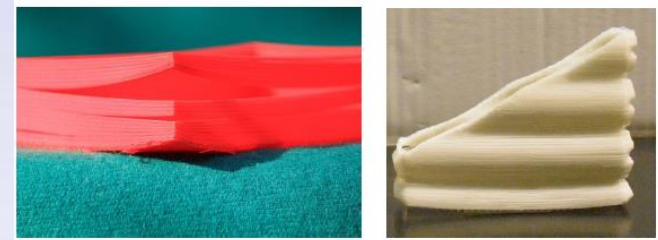
### Two types

- ◆ 2D (area filling at once): raster-based
- ◆ 1D scanning tool path: vector-based

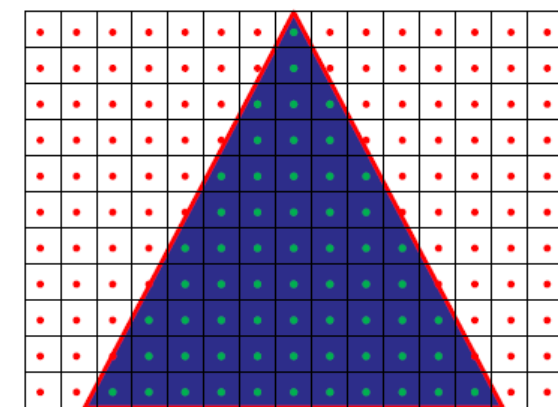
### Factors

- ◆ Surface accuracy
- ◆ Build time
- ◆ Mechanical properties:  
stiffness, strength, distortion

- ◆ Orientation
- ◆ Support structure
- ◆ Slicing
- ◆ **Path planning**
- ◆ Machine instructions

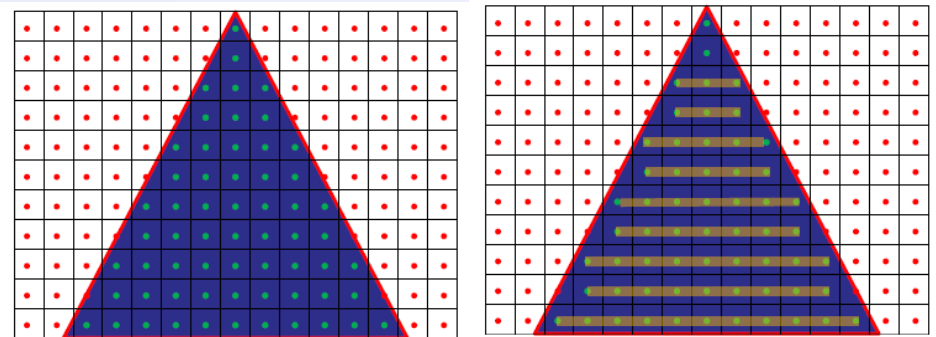


For raster-based: e.g., inkjet



After voxelization,  
superimpose a voxel grid

For vector-based: e.g., SLA



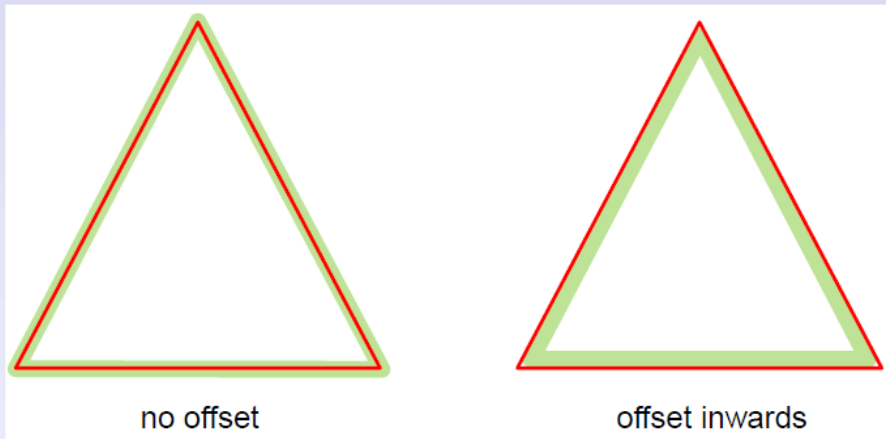
1. Superimpose a voxel grid
2. Rows and columns used as tool paths

# How does it Work

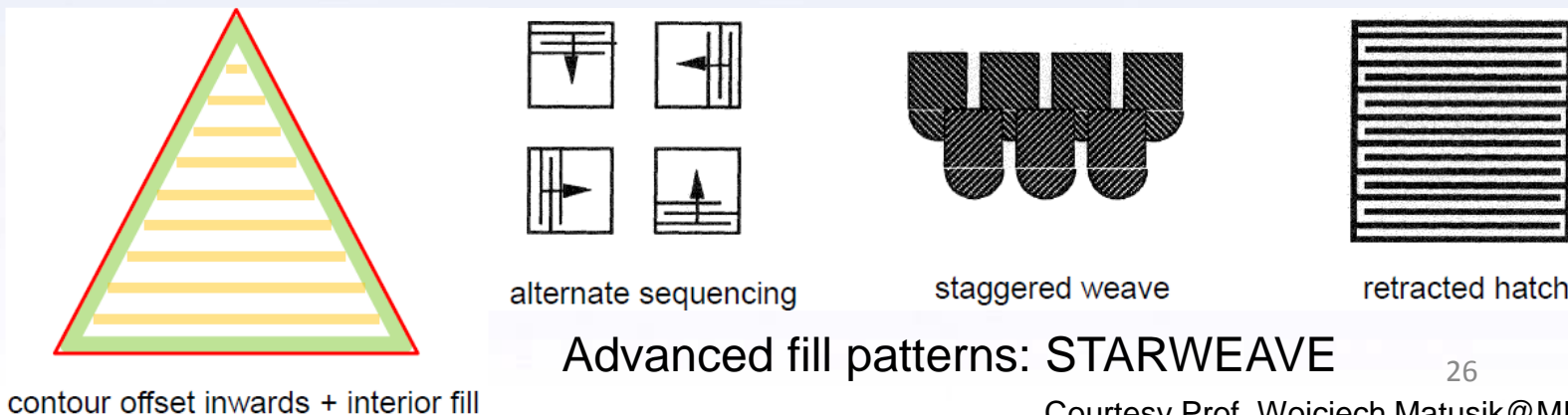
## ❖ Path planning

For vector-based

### ❖ Tracing contours: improved surface accuracy



### ❖ Tracing contours + filling interiors



- ❖ Orientation
- ❖ Support structure
- ❖ Slicing
- ❖ **Path planning**
- ❖ Machine instructions

## ❖ Machine Instructions

- ❖ **Raster-based, e.g., inkjet:**  
**proprietary, can be exported as image files (PNG, BMP, etc.)**

- ❖ **Vector-based, e.g., FDM:**

1. **G-code (dominant);**
2. **SLI by 3D Systems**

### **G-Code**

- ❖ **Developed at MIT in 1950s for CNC milling**

- ❖ **Simple instructions telling machine**

- ❖ **where to move**
- ❖ **how fast to move**
- ❖ **what path to move**

Sample instructions:

**-G00: Rapid move**

- does not necessarily move in a single straight line between start point and end point. It moves each axis at its max speed until its vector is achieved.

**-G01: Linear interpolation**

- specify the start and end points, and the control automatically calculates the intermediate points to pass through that will yield a straight line

**-G02: Circular interpolation, clockwise**

- ❖ **Orientation**

- ❖ **Support structure**

- ❖ **Slicing**

- ❖ **Path planning**

- ❖ **Machine instructions**

# How does it Work

## ❖ Post-processing – depends on process

### Steps:

- ❖ Remove the part from the build platform and depowder (if powder based) and cleaning;
- ❖ Remove the support structures from the part using appropriate tools
- ❖ Post-curing (SLA)
- ❖ Surface finishing

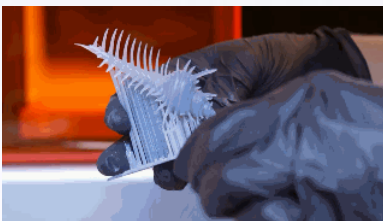
## ❖ Example of SLA



Remove build platform and the part



Rinse in IPA



Remove supports



Finish w. sand paper and mineral oil



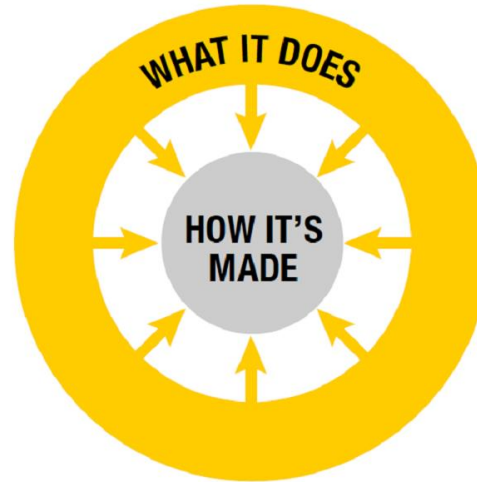


# Advantages

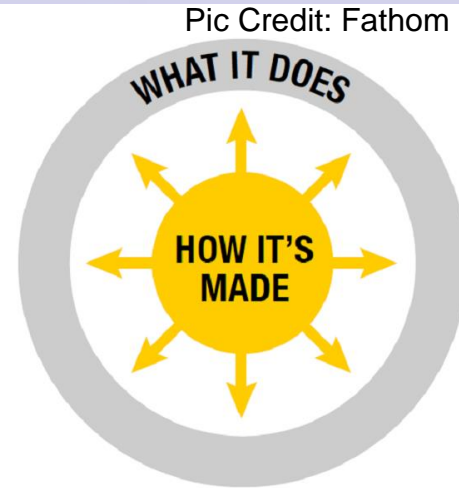
## Design Freedom

Complexity is nearly free

- Geometry
- Material
- System

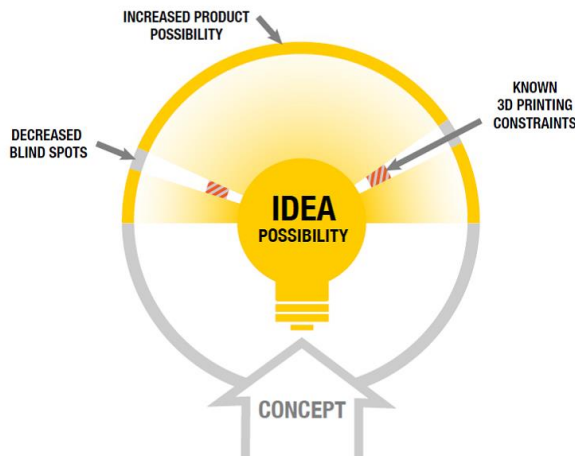


**ADDITIVE MFG**  
Drives Innovation

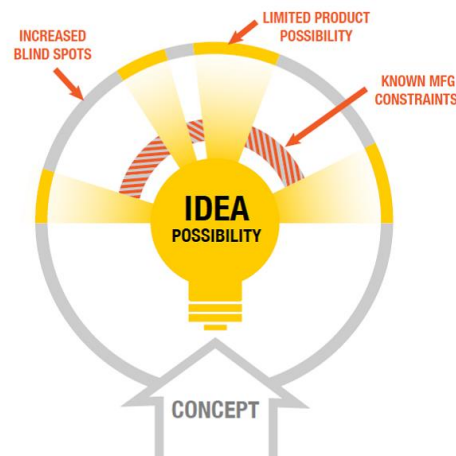


**TRADITIONAL MFG**  
Limits Design

## DESIGN FREEDOM: Increase Product Possibility



**ADDITIVE MFG**  
Increase Design Possibility  
with Minimal Blind Spots and Constraints

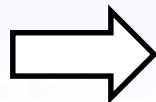


**TRADITIONAL MFG**  
Limits Design Possibilities  
with Many Blind Spots and Constraints

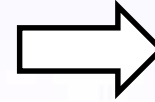
## ❖ Digital



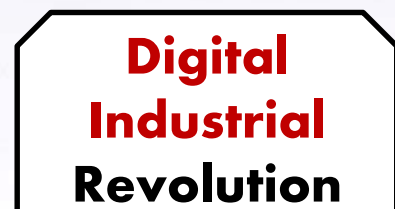
Mass Production



Customization

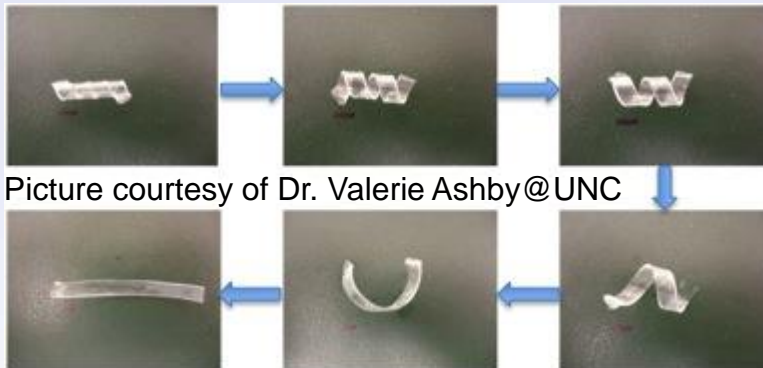


Mass Customization



## ❖ Integrated smart structures

- ❖ Reduced volume and weight (make everything more “compact” and “wearable”)
- ❖ Smart: structures that can sense, communicate, respond, and process information; (no more “dead” structures)

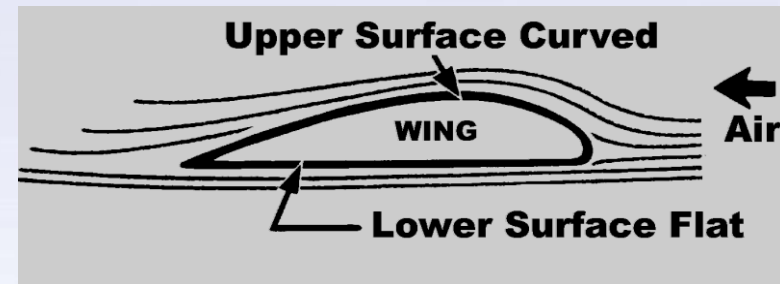


Picture courtesy of Dr. Valerie Ashby@UNC

Shape memory polymers – change structure at external stimulus



Mimosa



Design a wing structure that can adapt its shape to the environment



Imagine: a shoe that can change size, color, and shape

- ❖ **Blur the boundary between physical and digital world**
- ❖ **Giving the autonomous producing capability to machines**
- ❖ **Life: sense, information processing, responding (executing instructions), metabolism + **autonomous reproduction****

What is AM

Applications

How does it work

Advantages

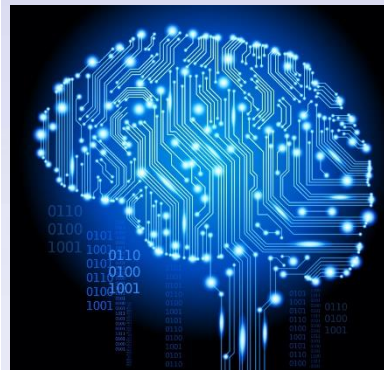
Opportunities

Challenges

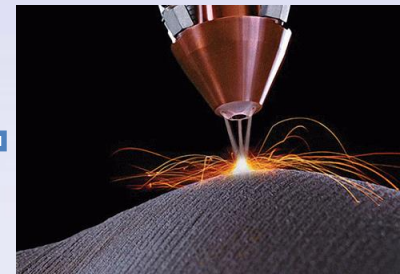
AM Industry



Robotics



Artificial Intelligence Internet of things

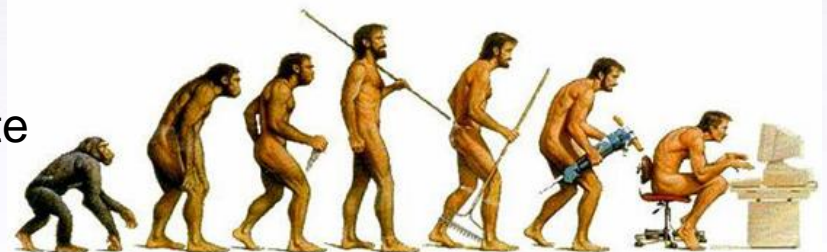


3D printing

## A self-evolving world that doesn't need humans



Self-Repair  
Self-Replicate  
Self-Evolve





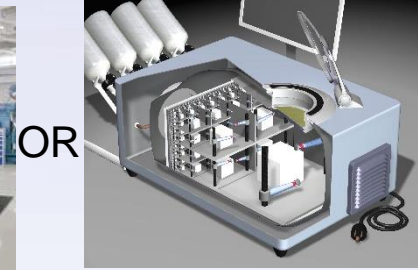
## ❖ Revolutionizing product value chain

### What we do now



Professional Design Mass Production Transportation Local distribution Shopping Mall

### What we will do when we get there



Custom Design  
with Professional  
Design Software

Internet

Local Production Center  
with 3D Printers

Desktop Factory

Need to digitalize most of our current products (we are currently only able to 3D print a negligible tiny portion of our current products)



## ❖ **TOO Slow** ( $< \sim 1000 \text{ cm}^3/\text{hr}$ )



Build a house brick by brick



Parallel building – scaling up

- ❖ **Material unit volume** ( $\text{resolution}^3$ ) – **use coarse resolution**
- ❖ **Deposition frequency** ( $\sim 10\text{kHz}$ ) or **scanning speed** ( $< \sim 1000 \text{ mm/s}$ ) – **increase frequency to MHz + parallel building**
- ❖ **Delay between layers** ( $< \sim 1\text{s}$ ) – **continuous building**
- ❖ **Post-processing** ( $\sim 1\text{x}$  of build time) – **eliminate it**

## ❖ Materials

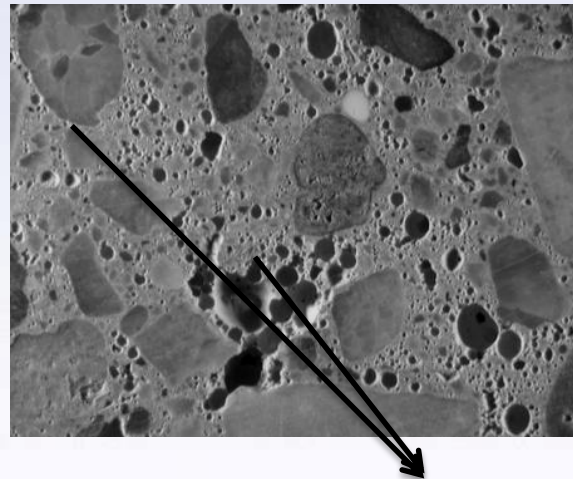
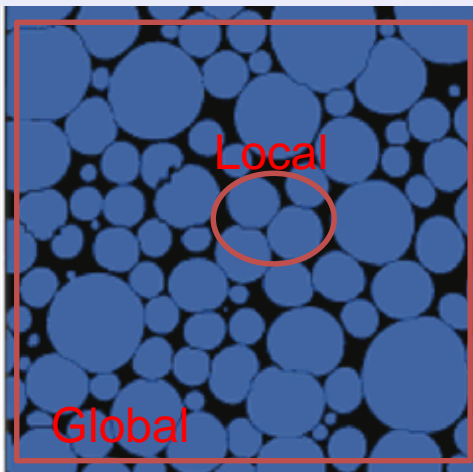
### ❖ Energy patterning

- ❖ **Common choices: photopolymer, thermoplastics, Titanium (alloys), steel;**
- ❖ **Difficult materials: aluminum, ceramics, biomaterials, etc.**

### ❖ Material patterning (sensitive to material properties)

- ❖ **Viscosity (e.g., inkjet, < ~40cP)**
- ❖ **Surface tension (e.g., syringe)**

## ❖ Properties



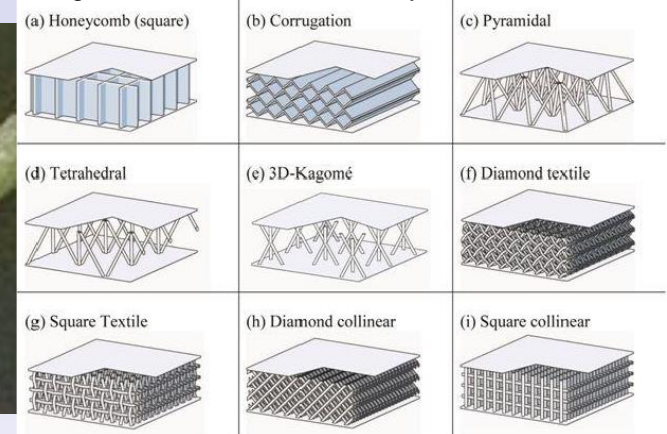
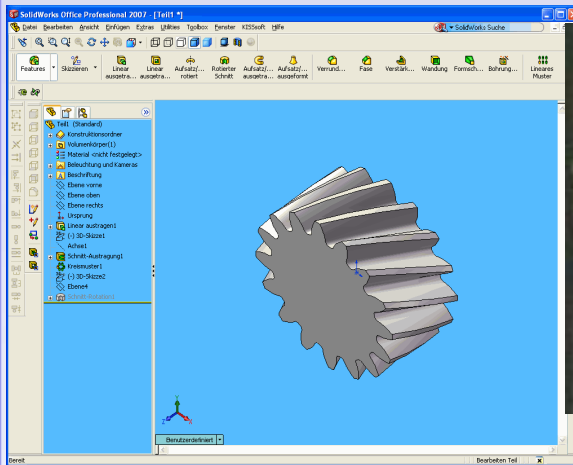
Voids/Material interfaces:  
Lead to stress concentration, etc.

Core idea of AM:  
material joining  
(reduce material  
interfaces) →  
undesired material  
interfaces lead to  
inferior material  
properties

# Challenges

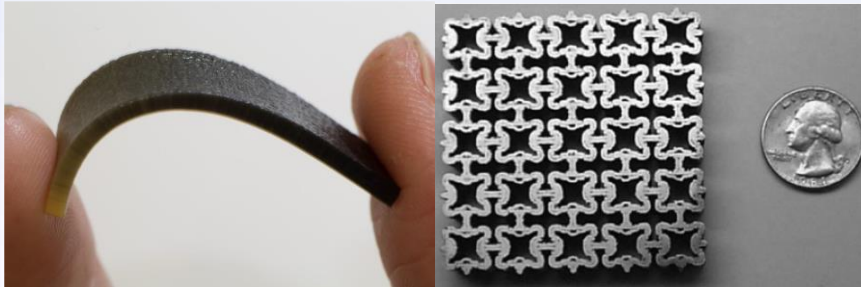
- ◆ **Design complexity (Mutliscale & multi-resolution) from design freedom**
  - ◆ **Geometry**
  - ◆ **Material composition**
  - ◆ **Local process parameters (open loop, repeatability)**

<http://www.virginia.edu/ms/research/wadley/cellular-materials.html>

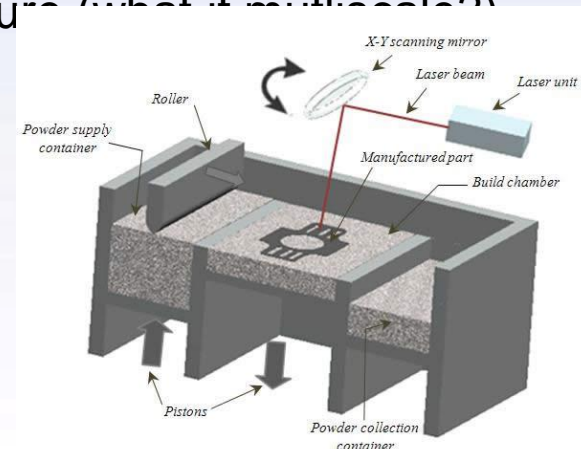


Current CAD system

Design and optimize lattice structure and cellular structure (what if multi-scale?)



Design of material composition (functional graded material, metamaterial)



Local process parameters



## ❖ Killer applications

### ❖ Faster, cheaper, better solution for large-scale common & important problems



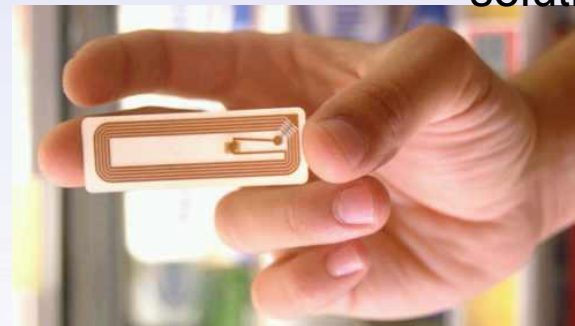
Aerospace (multi-billion dollar industry)



Align Technology (multi-billion dollar industry)



Need **MORE** SIMPLE IDEAS for better solutions



Printed RFID (multi-billion dollar industry)



Printed flexible display

What is AM

Applications

How does it work

Advantages

Opportunities

Challenges

AM Industry





# AM Industry

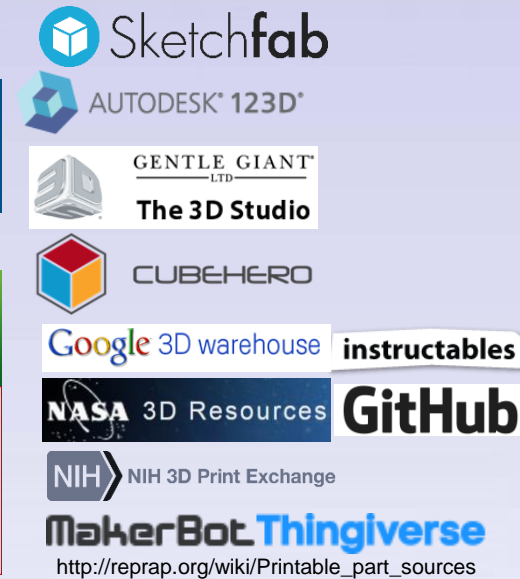
## 3D Content Provider



CAD

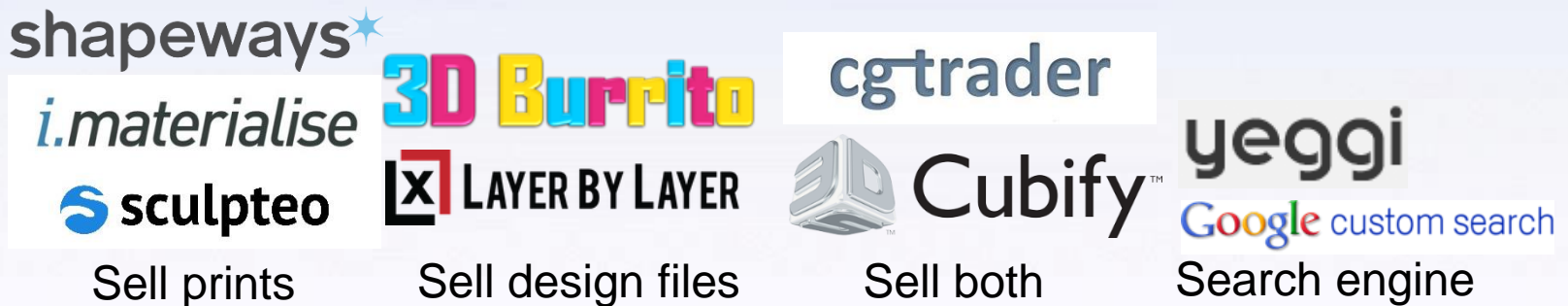


3D Scanners



Online Repositories

## Marketplace (Share, buy, and sell designs)



Sell prints

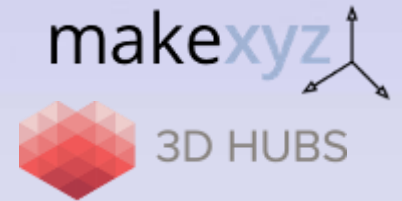
Sell design files

Sell both

Search engine

<http://makingsociety.com/2013/07/37-3d-printing-marketplaces-to-share-buy-and-sell-3d-designs/>

## 3D Printing service



Connect to local  
3D printers (cloud)























Provide local store printing service



<http://www.wohlersassociates.com/service-providers.html>

Solution providers (industrial)

## Machine suppliers

	Major Players	Materials
<b>SLA</b>	 3DSYSTEMS™  <b>Stratasys</b> FOR A 3D WORLD™  <b>envisionTEC.</b>	<b>Photopolymers</b>
<b>FDM</b>	 <b>Stratasys</b> FOR A 3D WORLD™  3DSYSTEMS™  <b>Stratasys</b> MakerBot INDUSTRIES  <b>RepRap</b>	<b>Thermoplastics</b>
<b>Inkjet</b>	 <b>OBJET</b>  STRATASYS® Make It Real™  3DSYSTEMS™  <b>Dimatix</b> FUJIFILM™  <b>PIXDRO</b>  <b>MicroFab</b> TECHNOLOGIES • INC.	<b>Photopolymer; Metal/ceramics in suspension</b>
<b>Powder (bed)</b>	 CAD TO METAL® Arcam AB®  <b>ExOne</b> DIGITAL PART MATERIALIZATION  3DSYSTEMS™  Z CORPORATION®  <b>RENISHAW</b>  <b>EOS</b> e-Manufacturing Solutions  <b>voxeljet SLM</b> Solutions GmbH  <b>hp</b>  <b>OPTOMECH</b> Production Grade 3D Printers... with a Material Difference	<b>Powders: Metal, ceramics, plastic, glass, plaster, sand, etc.</b>

## ❖ Software (convert STL files to machine instructions)



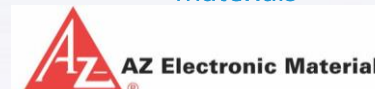
[http://reprap.org/wiki/Useful\\_Software\\_Packages](http://reprap.org/wiki/Useful_Software_Packages)



Open source

Closed source

## ❖ Material suppliers



Filaments

Photopolymers

Printable inks



# AM Industry

## Customers



Aerospace & Defense



Architecture & Geo



Automotive



Education



Energy



Healthcare



Jewelry



Hobbyist



Consumer

<http://www.3dsystems.com/solutions/overview>

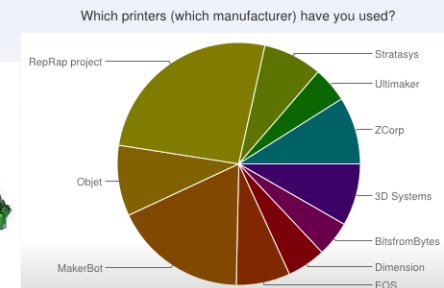
## Open source community



Evan Malone and Hod Lipson  
Cornell, 2006, syringe based  
(dying after 2012)



Adrian Bowyer, U of Bath, UK; Self-replicating,  
FFF based, Arduino-based control, Thriving





What is AM

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